



BSI Standards Publication

Semiconductor devices – Micro-electromechanical devices

Part 31: Four-point bending test method for interfacial adhesion energy of layered MEMS materials

National foreword

This British Standard is the UK implementation of IEC 62047-31:2019.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Amendments/corrigenda issued since publication

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